


MATERIAL DECLARATION SHEET



Material Number	CRM2512 series (over 1 Ω)			
Product Line	High power chip resistors			
Compliance Date	09/01/2016			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	34.7435	Aluminum oxide	1344-28-1	96	83.687	87.174
				Silicon dioxide	14808-60-7	2	1.7435	
				Magnesium oxide	1309-48-4	2	1.7435	
2	Top conductor	Silver	0.6157	Silver	7440-22-4	100	1.545	1.545
3	Bottom conductor	Silver	0.3152	Silver	7440-22-4	100	0.791	0.791
				Silver	7440-22-4	40	0.383	0.959
4	Resistor	Ruthenium Oxide	0.3821	Ruthenium(IV) oxide	12036-10-1	20	0.192	
				Palladium	7440-05-3	15	0.144	
				Lead	7439-92-1	14.9	0.143	
				Glass	65997-17-3	10.1	0.097	
5	First encapsulating	Glass	0.3685	Glass	65997-17-3	92	0.851	0.925
				Chromium(III) oxide	1308-38-9	8	0.074	
6	Overcoat	Resin	0.8454	Resin	25036-25-3	100	2.121	2.121
7	Side conductor	Silver	0.8142	Silver	7440-22-4	85	1.737	2.043
				Resin	9003-36-5	15	0.306	
8	Plating (Middle)	Nickel	0.6872	Nickel	7440-02-0	100	1.724	1.724
9	Plating (Outer)	Tin	1.0308	Tin	7440-31-5	100	2.586	2.586
10	Marking	Resin	0.0525	Resin	29690-82-2	70	0.092	0.132
				Titanium oxide	1317-80-2	30	0.040	
Total weight			39.8551					

This Document was updated on: 09/01/2016

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 7 (c)-1 Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in

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capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.